

Upgrade of the ATLAS Monitored Drift Tube Front-end Electronics for the HL-LHC

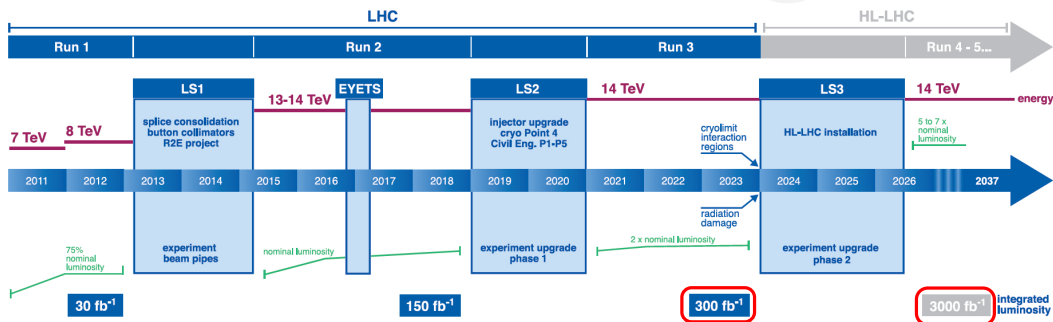
O. Kortner on behalf of the ATLAS muon collaboration

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ICHEP 2018, Seoul, 05.07.2018

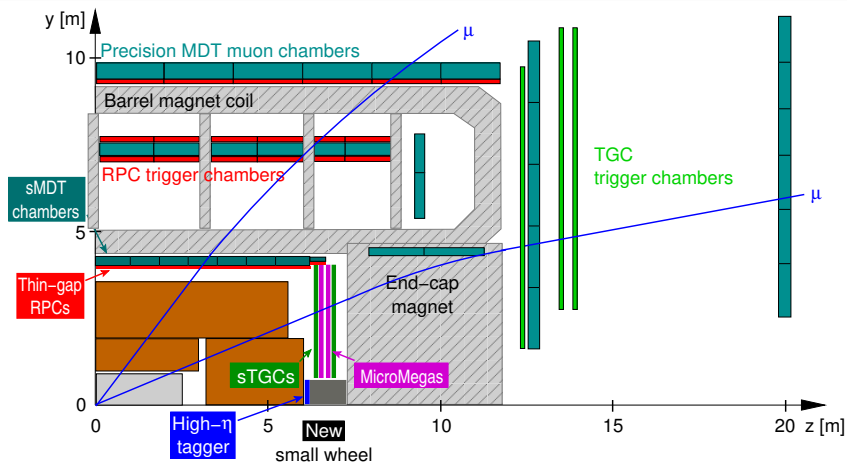
The roadmap to High-Luminosity LHC

LHC / HL-LHC Plan



- Plan to increase the LHC luminosity by an order of magnitude.
- Increase of the particle fluxes/rates by an order of magnitude from the LHC to the HL-LHC requires a major detector upgrade.
- Muon spectrometer EYETS upgrade in two steps during long shutdowns 2 and 3.

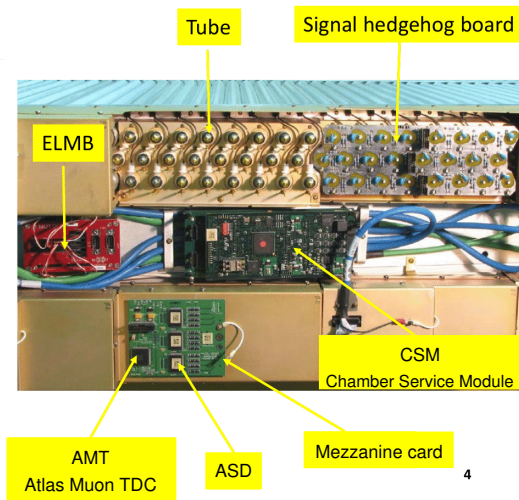
The ATLAS muon spectrometer at the HL-LHC



- New small wheel with high-resolution trigger chambers to reject fake muon triggers and improve momentum resolution at trigger level.
- New **thin-gap RPCs** to close acceptance gaps of the barrel muon trigger.
- New **sMDT chambers** to free space for new RPCs.
- New 1st level muon trigger using MDT chamber information.
- + New on- and off-chamber electronics for new trigger architecture.

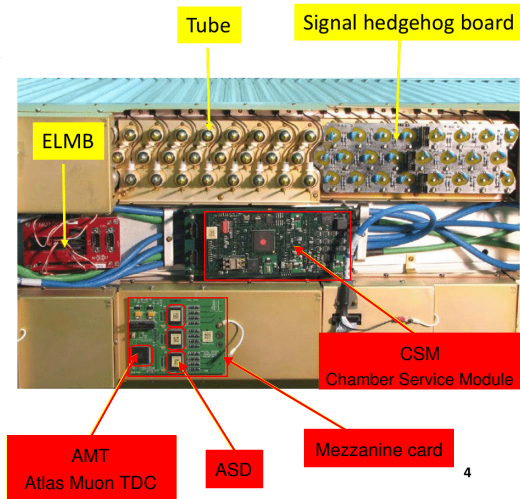
On-chamber MDT read-out electronics

Present read-out electronics



- Read-out in groups of 24 tubes (3×8 or 4×6).
- Passive part: Hedgehog cards with coupling capacitors.
- Active part:
 - 3 ASDs \rightarrow TDC
 - 18 TDCs \rightarrow CSM \rightarrow off-detector elx

On-chamber MDT read-out electronics



Present read-out electronics

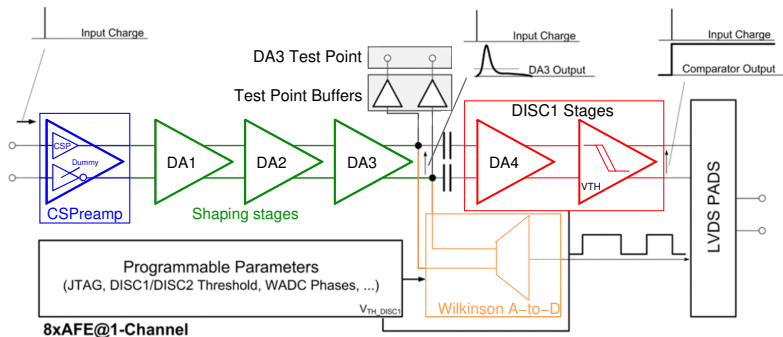
- Read-out in groups of 24 tubes (3×8 or 4×6).
- Passive part: Hedgehog cards with coupling capacitors.
- Active part:
 - 3 ASDs→TDC
 - 18 TDCs→CSM→off-detector elx

Trigger requirements at the HL-LHC

- 1st level trigger rate will be increased from the present 100 kHz to 1-4 MHz.
- ⇒ Present TDCs and CSMs incompatible with trigger rates >200 kHz.
- ⇒ **New on-chamber electronics needed for operation at the HL-LHC!**

New Amplifier Shaper Discriminator (ASD) chip

- Present “legacy” ASD chip in 500 nm Agilent technology (**obsolete**).
- New ASD chip:
 - In 130 nm Global Foundries CMOS technology.
 - Design follows legacy chip with a fix of a specific design error of the legacy chip in the output logic.
- Block diagram of the new ASD chip

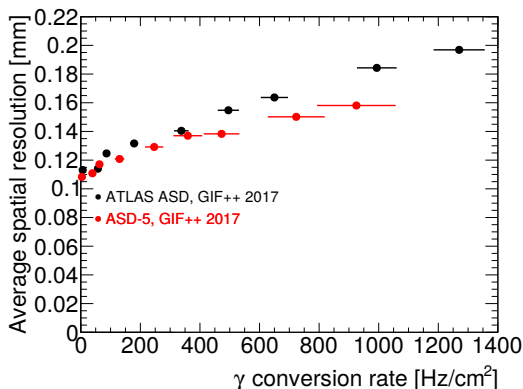


- **Differential charge sensitive preamplifier.**
- **Bipolar shaping with ion tail cancellation.**
- **Wilkinson ADC** for time-walk corrections to **discriminated signals.**

Test of the new ASD chip

- The final version of the new ASD has been tested with test pulses and on an MDT chamber in the GIF++ at CERN.

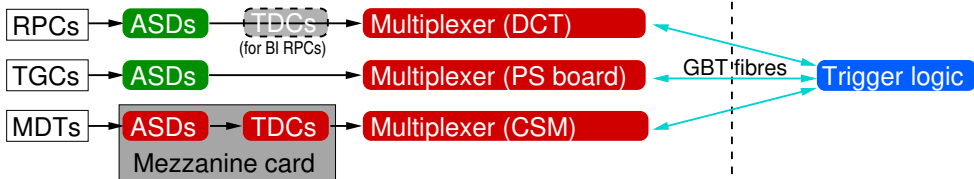
Parameter	Unit	Specs	Legacy ASD	New ASD
Signal peaking time	ns	15	14.4	12
Amplification	mV/fC	8.9	10	21
Noise r.m.s	mV	8.5	8	4
Threshold spread	mV		12-16	4
Power consumption	mW		300	360



Performance of the new chip better than the legacy chip in terms of noise, threshold spread, and amplification leading to a better achievable spatial resolution!

Read-out scheme and data rates at the HL-LHC

On-detector electronics



- Streamed read-out of all muon chambers at the HL-LHC to minimize trigger latency.

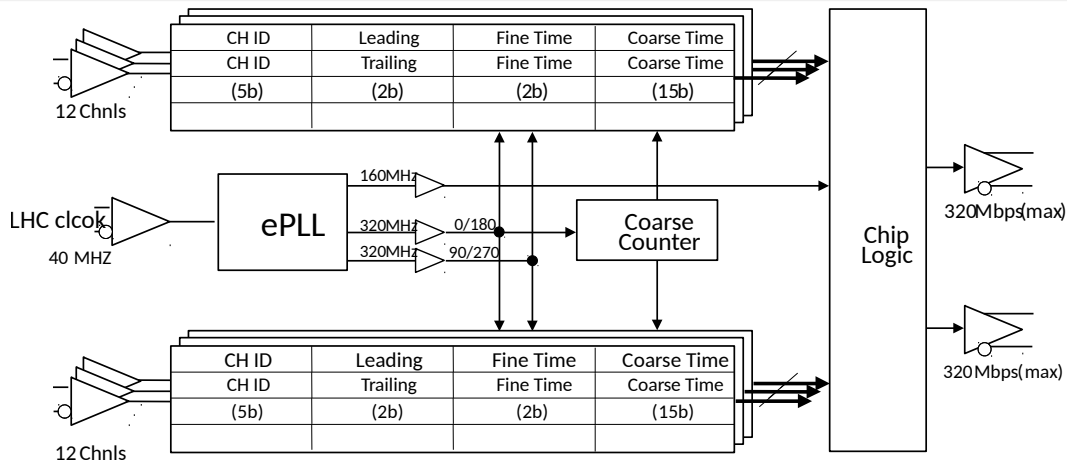
- | Max. rate
[kHz/tube] | Mode | TDC output
rate | CSM output
rate |
|-------------------------|-----------|--------------------|--------------------|
| 400 | Edge mode | 2×288 Mbps | 2×5.2 Gbps |
| 400 | Pair mode | 1×384 Mbps | 1×6.9 Gbps |

Edge mode: 24 bits for leading edge + 24 bits for trailing edge.

Pair mode: 32 bits for leading+trailing edge.

Data transfer after with 8b/10b encoding.

New Time-to-Digital Converter (TDC) chip



- Time measurement:

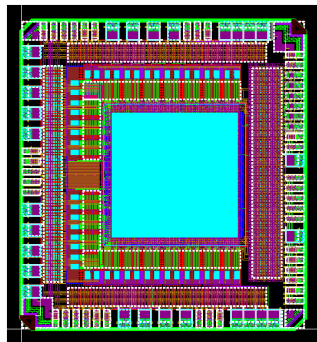
- Coarse time in steps of 3.125 ns (15 bits).
- Fine time in step of $3.125 \text{ ns}/4 = 0.7815 \text{ ns}$ (2 bits).

- Technology:

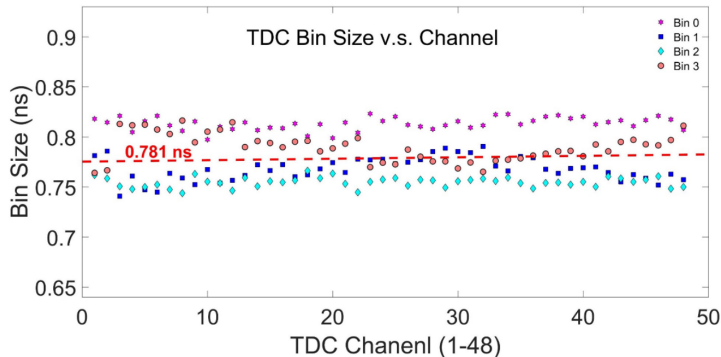
- TDC demonstrator in 130 nm Global Foundries CMOS technology.
- Prototypes and final chip in 130 nm TSMC CMOS technology.

Results from the TDC demonstrator

Floor plan



Time resolution



Excellent uniformity. Differential and integral non-linearity: ± 40 ps!

CSM tasks

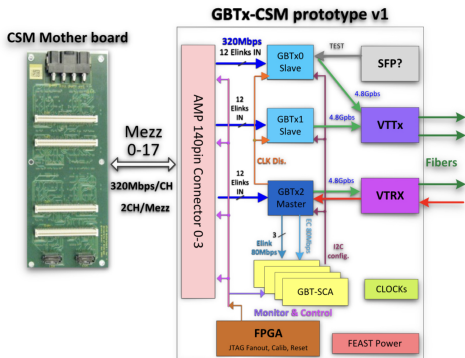
- Multiplexer collecting the data from up to 18 mezzanine cards and sending them downstream via high-speed optical links.
- Distribution of configuration information to the mezzanine cards via down-link.
- Passing of monitoring information from mezzanine cards and CSM via up-link.

Boundary conditions

- Design must be allow for the reuse of the existing cables from the mezzanine cards.
- Backward compatibility with legacy mezzanine cards for chambers where these cards are inaccessible for exchange with new cards.

Design options for the new CSM

Baseline: GBTx based



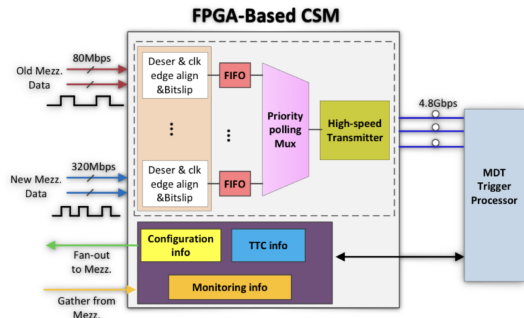
Advantages

- Support of low-power GBT.
- Radiation hard.

Disadvantage

- Difficult to achieve backward compatibility with legacy electronics.

Alternative: FPGA based



Advantages

- Reprogrammable.
- Backward compatibility with legacy electronics.

Disadvantages

- Limited radiation hardness.
- No support of low-power GBT so far.

- New ATLAS trigger scheme (1-4 MHz 1st level trigger rate) requires new MDT chamber front-end electronics:
 - New on-chamber mezzanine cards with new ASD and TDC ASICs.
 - New on-chamber multiplexer, so-called “CSM”.
- New ASD design completed in 130 nm Global Foundries CMOS technology, chip production in 2018/2019.
- TDC demonstrator in 130 nm Global Foundries CMOS technology completed and successfully tested in 2017.
First prototype in 130 nm TSMC CMOS technology in preparation.
- Two options for CSM prototypes:
 - Baseline: GBTx based CSM.
 - Alternative for read-out of chambers with legacy electronics: FPGA based CSM.